ABSTRACT

An object of the present invention is to provide a simple process for manufacturing a flexible printed wiring board having fine metal bumps.

A resin coating 21 and a resist film 24 are formed in this order on the surface of a metal film 11 and on the surface of each metal bump 16 formed on the metal film 11, and a pressure is applied on the surface to depress the resist film 24 on the metal bump 16, followed by etching. As the surface of the resin coating 21 is partially exposed at the depressed portion of the resist film 24, etching of the resin coating 21 proceeds from that portion to bulge the surface of the metal bump 16 from the resin coating 21. If the resist film 24 is formed after a flexible resin coating 22 is formed on the rigid resin coating 21, the flexible resin coating 22 can serve as an adhesive layer.